

PCN Number:	20140313000	PCN Date:	03/13/2014
Title:	Qualification of JCAP as additional Assembly/Bump/Test site for select WCSP devices		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
		Dept:	Quality Services
*Proposed 1st Ship Date:	06/13/2014	Estimated Sample Availability:	Date Provided at Sample request
Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input checked="" type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Part number change

PCN Details

Description of Change:

This change notification is to announce the qualification of JCAPAT as an additional Assembly, bump and test site for the devices listed below. There are no BOM differences between the devices currently assembled in SCSAT and JCAPAT.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
SCSAT	Assembly Site Origin (22L)	ASO: SCS
JCAPAT	Assembly Site Origin (22L)	ASO: JCP

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
 LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Topside Device marking:
 Assembly site code for SCSAT= G
 Assembly site code for JCAPAT= P

Product Affected:			
HPA01181YZPR	TPS22922YZPR	TPS22949AYZPR	TPS22949YZPR
TPS22922BYZPR			

Qualification Data: Approved April, 2008					
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.					
Qualification Device: TS3DS26227YZT (MSL LEVEL1-260C)					
Assembly Site:	JCAPAT	Bump Composition:	SnAgCu		
# Pins-Designator, Family:	12-YZT, DSBGA	Bump Diameter:	0.225mm		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Sample Size / Fail			
		Lot#1	Lot#2	Lot#3	
**Steady-state Life Test	150C (168, 300 Hrs)	116/0	116/0	116/0	
**High Temp. Storage Bake	170C (168, 420hrs)	77/0	77/0	77/0	
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0	
**Unbiased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0	
**T/C -55C/125C	-55C/+125C (500, 1000 Cyc)	77/0	77/0	77/0	
Visual / Mechanical	Per Manufacturing specifications	pass	pass	pass	
Solderability	Steam age, 8 hours	22/0	22/0	22/0	
Bump-shear	(# of bumps per lot)	pass	pass	pass	
**Preconditioning: Level 1-260C					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com